PRODUCT CHANGE NOTICE

Wafer Fabrication Process Improvement for the Listed Intersil HVSIGATE technology Products

Refer to:
PCN12004

Date: January 19, 2012

intersil SIMPLY SMARTER™

January 19, 2012

To: Our Valued Intersil Customer

Subject: **Wafer Fabrication Process Improvement for the Listed Intersil HVSIGATE Technology Products –** *Intersil Palm Bay, Florida Facility*

This notice is to inform you of a pending change to the wafer fabrication process used for the listed HVSIGATE technology products. The changes implement a planarization process and affect the glassivation material composition and thickness.

- Glassivation composition and thickness changed from nitride (8kÅ) to an oxide (14kÅ) and nitride (8kÅ) stack.
- Planarization process implemented to enhance metal step coverage.

The changes will improve the long-term reliability of these products and Intersil's ability to meet customer delivery requirements. The qualification activities are complete as of the date of this notice.

Products affected:

DG401DVZ
DG401DVZ-T
DG401DYZ
DG401DYZ-T
DG403DVZ
DG403DVZ-T
DG403DYZ
DG403DYZR5485
DG403DYZ-T
DG403DYZ-TR5485
DG403DYZ-TS2457
DG403W
DG406DJZ
DG406DYZ
DG406DYZ-T
DG407DJZ
DG407DYZ
DG407DYZ-T
DG408DJZ
DG408DVZ
DG408DVZ-T
DG408DVZ-TR5321
DG408DVZ-TS2568
DG408DYZ
DG408DYZ-T
DG409DJZ
DG409DVZ
DG409DVZ-T
DG409DVZ-TR5321
DG409DYZ
DG409DYZ-T
DG411DJZ
DG411DVZ
DG411DVZR5485
DG411DVZ-T
DG411DYZ
DG411DYZR5485
DG411DYZ-T
DG411DYZ-TR5485
DG412DJZ
DG412DVZ
DG412DVZ-T
DG412DVZ-TR5321
DG412DYZ
DG412DYZR5485
DG412DYZ-T
DG413DJZ
DG413DVZ
DG413DVZ-T
DG413DYZ
DG413DYZ-T
DG441DJZ
DG441DVZ
DG441DVZ-T
DG441DVZ-TR5485
DG441DYZ
DG441DYZR5485
DG441DYZ-T
DG441DYZ-TR5485
DG442DJZ
DG442DVZ
DG442DVZ-T
DG442DYZ
DG442DYZR5485
DG442DYZ-T
DG442DYZ-TR5485
DG444DVZ
DG444DVZ-T
DG444DYZ
DG444DYZR5485
DG444DYZ-T
DG444DYZ-TR5485
DG445DVZ
DG445DVZ-T
DG445DYZ
DG445DYZ-T

The technology qualification plans for process related changes are designed using JEDEC, MIL-PRF-38535, and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. There will be no change to the product design, WAT (Wafer Acceptance Test), wafer level electrical test (circuit probe), package level electrical test, marking, or product datasheet specifications. Parts affected by this change are identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product fabricated using the improved process beginning ninety days from the date of this notification or upon depletion of existing inventory.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
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PCN12004 –Qualification Summary

HVSIGATE Qualification Results (Plastic) :

STRESS	SS	hrs	Down Points	Status
HTOL	80	1000	168, 500, 1000	0/80 at 168 hrs 0/80 at 500 hrs 0/80 at 1000 hrs
PRECON L3		L3 Pb Free		Complete no failures
THB	78	1000	500, 1000	0/78 at 500 hrs 0/78 at 1000 hrs
bHAST	78	96	96	0/78 at 96 hrs Passed Stress
Temp Cycle	78	1000	500, 1000	0/78 at 500 cy 0/78 at 1000 cy Passed Stress
MRT	22	MRT11174		Level 3 Pb Free MRT11174

HVSIGATE Qualification Results (Hermetic) :

Stress	Condition	5962-9073101MEA	5962-9204201MEA
Group C	C-1	0/45 (1 lot)	0/45 (1 lots)